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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A center-electrode assembly comprising:
a ferrite;
center-electrode patterns and insulating films deposited on the top surface of the ferrite;
a conductive pattern formed on the bottom surface of the ferrite; and
connecting electrodes directly formed on sides of the ferrite; wherein
the connecting electrodes electrically connect the center-electrode patterns and
the conductive pattern; and
said connecting electrodes, said center-electrode pattern and said conductive pattern are comprised of at least one of a plated conductive material, a printed
conductive material, a sputtered conductive material, a vapor deposited conductive
material, and an applied paste conductive material formed directly on the sides, on the
top surface and on the bottom surface, respectively, of the ferrite.

Claim 2 (original): A nonreciprocal circuit device comprising:
a permanent magnet;
a center-electrode assembly according to Claim 1 to which a direct-current
magnetic field is applied by the permanent magnet; and
a metallic case accommodating the permanent magnet and the center-electrode
assembly.

Claim 3 (original): A communication apparatus comprising a nonreciprocal circuit

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device according to Claim 2, and connected thereto, at least one of a transmitting circuit and a reception circuit.

Claim 4 (original): A communication apparatus comprising a center-electrode assembly according to Claim 1, and connected thereto, at least one of a transmission circuit and a reception circuit.

Claim 5 (currently amended): A method for manufacturing a center-electrode assembly comprising the steps of:

forming through-holes in a ferrite mother board;

alternately depositing a center-electrode pattern and an insulating film on the top surface of the ferrite mother board, the center-electrode pattern is formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method; and

forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;

cutting a center-electrode assembly from the ferrite mother board by cutting the ferrite mother board at intervals of a predetermined size; and

forming connecting electrodes in the through-holes in the center electrode assembly by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method and a conductive paste applying method to electrically connect the center-electrode patterns formed on the top surface and the conductive pattern formed on the back surface.

Claim 6 (previously presented): A center-electrode assembly according to claim 1, wherein the connecting electrodes are formed on grooves formed in the sides of the ferrite.

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Claim 7 (previously presented): A center-electrode assembly according to claim 1, further comprising:

ports directly formed on the sides of the ferrite; wherein

the ports are electrically connected with the connecting electrodes via the center-electrode patterns.

Claim 8 (previously presented): A center-electrode assembly according to claim 7, further comprising:

gaps formed on the bottom surface of the ferrite; wherein

the gaps are provided between ends of the ports and an end of the conductive pattern.

Claim 9 (withdrawn): A center-electrode assembly according to claim 1, further comprising:

ports directly formed on the upper surface of the ferrite; wherein

the ports are electrically connected with the connecting electrodes via the center-electrode patterns.

Claim 10 (currently amended): A center-electrode assembly comprising:

a ferrite;

center-electrode patterns and insulating films laminated on the top surface of the ferrite;

a conductive pattern formed on the bottom surface of the ferrite, and

connecting electrodes formed on the sides of the ferrite; wherein

the connecting electrodes electrically connect the center-electrode patterns and the conductive pattern; and

said connecting electrodes, said center-electrode pattern and said conductive

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pattern are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material, and an applied paste conductive material formed directly on the sides, on the top surface and on the bottom surface, respectively, of the ferrite.